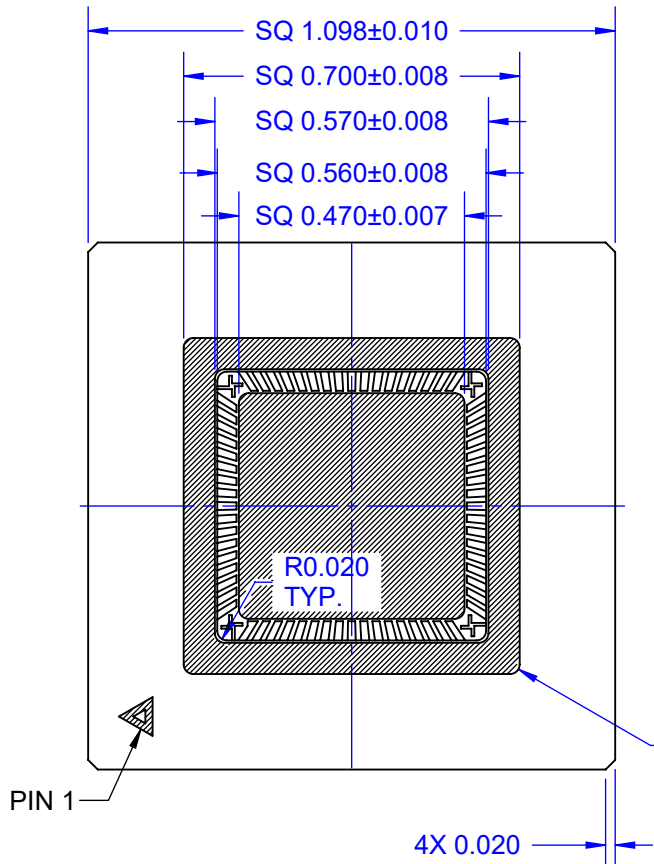
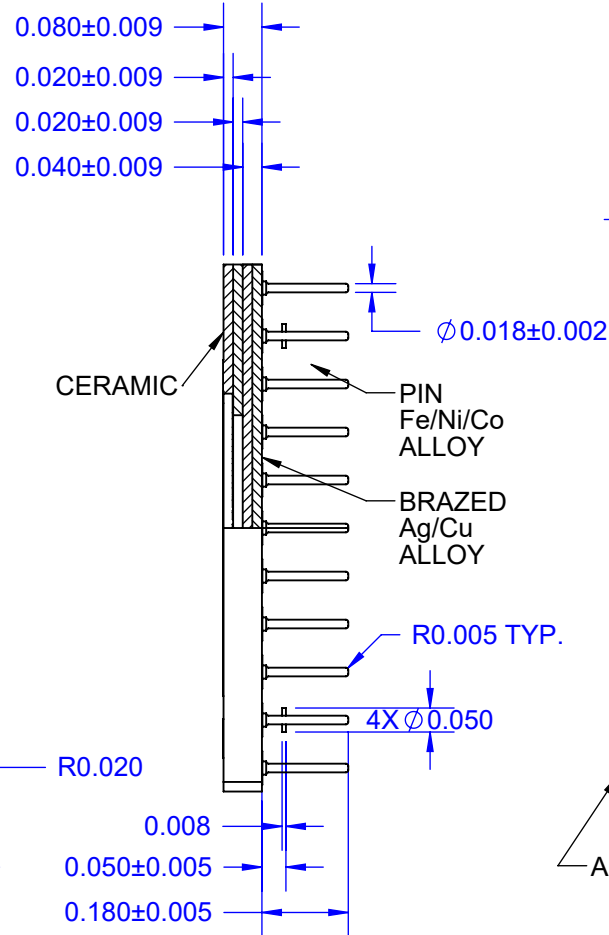


TOP VIEW

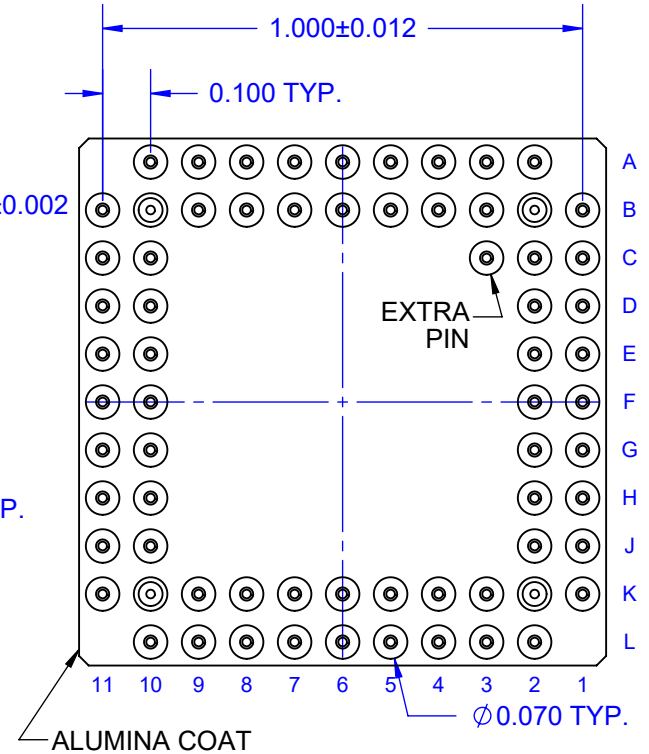


DIE PAD
 0.470 x 0.470 Inch
 11.93 x 11.93 mm

SIDE VIEW



BOTTOM VIEW



NOTE: ACTUAL PIN COUNT 69L
 INCLUDING EXTRA PIN.

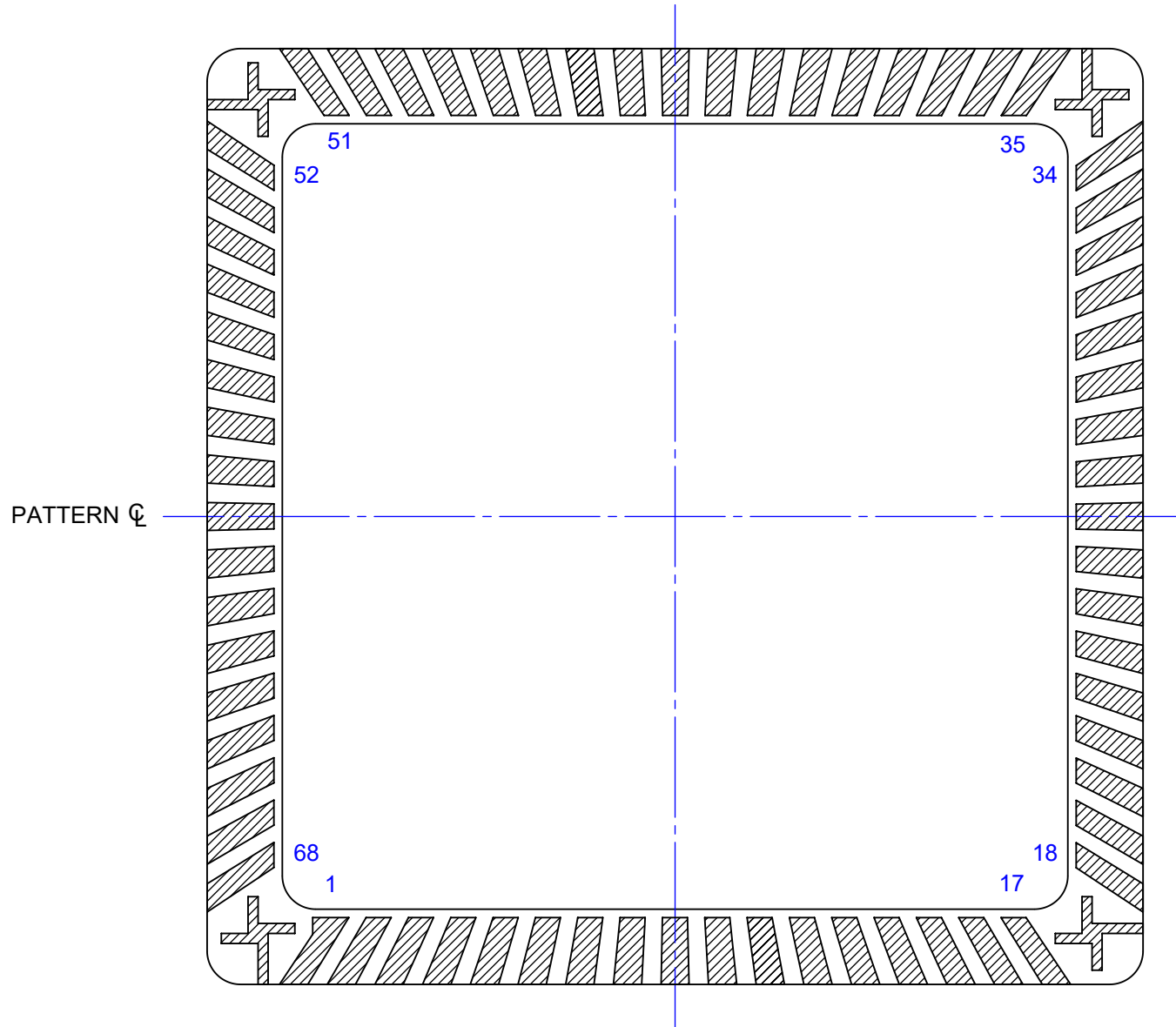
NOTES: (Unless Otherwise Specified).

- DIMENSIONS IN inches.
- ALL EXPOSED METAL AND METALLIZED AREA SHALL BE GOLD PLATED. 60 MICRO INCH MIN. THICKNESS. OVER NICKEL PLATED.
- SEAL AREA AND DIE ATTACH AREA SHALL BE ISOLATED.
- LEAD RESISTANCE PAD Nr 1, 9, 18, 28, 35, 43, 60 - 200 MILLI OHM MAX
ALL OTHERS 1000 MILLI OHM MAX.

APPROVALS	DATE	TopLine®			
DRAWN T. Au	06/03/16				
ENG M. Hart	06/03/16	TITLE CPGA68-11x11-N470 CERAMIC PIN GRID ARRAY			
MFG		SCALE 2.5:1	SIZE A	DRAWING NO. 201295	REV A
QA		DO NOT SCALE DRAWING		SHEET 1 OF 4	
CUST					
REVISED					

BOND PAD

PATTERN \varnothing



TopLine[®]

TITLE CPGA68-11x11-N470
CERAMIC PIN GRID ARRAY

SCALE 10:1	SIZE A	DRAWING NO. 201295	REV A
---------------	-----------	-----------------------	----------

DO NOT SCALE DRAWING

SHEET 2 OF 4

BOND PAD NET LIST

W/B NO.	PIN NO.
1	B2
2	B1
3	C2
4	C1
5	D2
6	D1
7	E2
8	E1
9	F2
10	F1
11	G2
12	G1
13	H2
14	H1
15	J2
16	J1
17	K1
18	K2
19	L2
20	K3

W/B NO.	PIN NO.
21	L3
22	K4
23	L4
24	K5
25	L5
26	K6
27	L6
28	K7
29	L7
30	K8
31	L8
32	K9
33	L9
34	L10
35	K10
36	K11
37	J10
38	J11
39	H10
40	H11

W/B NO.	PIN NO.
41	G10
42	G11
43	F10
44	F11
45	E10
46	E11
47	D10
48	D11
49	C10
50	C11
51	B11
52	B10
53	A10
54	B9
55	A9
56	B8
57	A8
58	B7
59	A7
60	B6

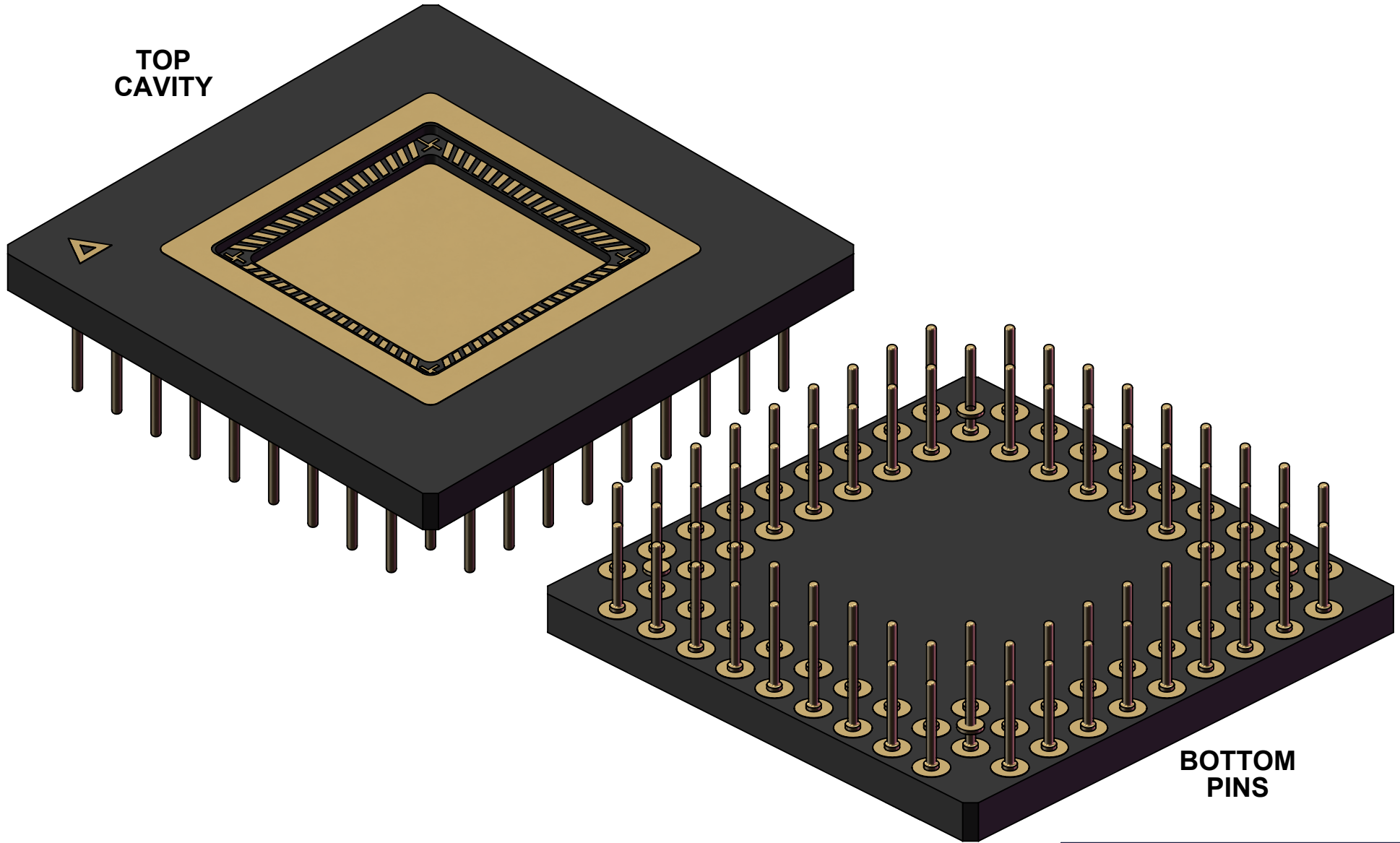
W/B NO.	PIN NO.
61	A6
62	B5
63	A5
64	B4
65	A4
66	B3
67	A3
68	A2

S/R	NC
D/A	NC
EXTRA PIN (C3)	C2

TopLine®			
TITLE CPGA68-11x11-N470 CERAMIC PIN GRID ARRAY			
SCALE NONE	SIZE A	DRAWING NO. 201295	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 4	

MODEL

TOP
CAVITY



BOTTOM
PINS

TopLine[®]

TITLE CPGA68-11x11-N470
CERAMIC PIN GRID ARRAY

SCALE 4:1	SIZE A	DRAWING NO. 201295	REV A
--------------	-----------	-----------------------	----------

DO NOT SCALE DRAWING

SHEET 4 OF 4